

Filename: PMP8703RevB - BoM.xls

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## PMP8703RevB - Bill of Material

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
12	C105, C106, C107, C108, C109, C110, C111, C112, C113, C114, C116, C118	47uF	Capacitor, Ceramic, 10V, X7R, 10%	1210	Std	Std
2	C17, C23	6.8nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C18	3.3uF	Capacitor, Ceramic, 16V, X7R, 10%	0805	Std	Std
1	C19	3.9nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
5	C2, C7, C20, C26, C39	100nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
2	C21, C24	220pF	Capacitor, Ceramic, 50V, NP0, 5%	0603	Std	Std
1	C34	4.7nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C40	1nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
6	C5, C6, C37, C38, C101, C102	22uF	Capacitor, Ceramic, 25V, X7R, 10%	1210	Std	Std
2	C8, C25	33nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
2	C9, C22	470pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
3	J1, J2, J3	ED120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35 inch	ED120/2DS	On Shore Technology
1	J4	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins
5	JP1, JP2, JP3, JP4, JP5	PEC03SAAN	Header, Male 3-pin, 100mil spacing,	0.100 inch x 3	PEC03SAAN	Sullins
1	L1	3.3uH	Inductor, SMT, 3.3uH, 5.4mOhm, 14.0A rms, 15.5A sat	10.9 x 10.0 mm	7443330330	Wurth Elektronik
1	L2	4.7uH	Inductor, SMT, 4.7uH, 12.4mOhm, 7.5A rms, 8.0A sat	8.4 x 7.9 mm	7443340470	Wurth Elektronik
2	Q1, Q2	CSD86330Q3D	MOSFET, Synchronous Buck NexFET Power Block	QFN-8 POWER	CSD86330Q3D	Texas Instruments
1	R1	33.2k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R10	7.32k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R11, R18	3.32k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R12	150	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R13	6.98k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R14, R25	1.00k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R15	45.3k	Resistor, Chip, 1/16W, 1%	0603	Std	Std

1	R19	4.53k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R2	86.6k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R21	113k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R23	86.6	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R26	5.76k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R27	11.0k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R28, R29	100k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R3	4.22k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	R4, R5, R22	1	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R6	40.2k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R7, R24	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
4	R8, R17, R20, R30	5.11	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R9, R16	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	SH1, SH2		Short jumper			
3	TP1, TP3, TP13	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
3	TP2, TP4, TP14	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
6	TP5, TP6, TP7, TP15, TP16, TP17	None	Test point, 40 mil SMT	None	None	None
6	TP8, TP10, TP12, TP18, TP19, TP21	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch	5011	Keystone Electronics
6	TP9, TP11, TP20, TP22, TP23, TP24	5012	Test Point, White, Thru Hole	0.125 x 0.125 inch	5012	Keystone Electronics
1	U1	TPS40322	IC, Dual Synchronous Buck Controller	QFN-32	TPS40322RHB	Texas Instruments

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